

11765
#4
Jca
5/28/03
EIVED

A circular stamp from the Office of Intellectual Property (OIP). The text "OIP" is at the top, "JC25" is at the top right, "MAY 27 2003" is in the center, and "PATENT & TRADEMARK OFFICE" is at the bottom.

~~~~~

Group Art Unit: 1765

RECEIVED  
MAY 28 2003  
GROUP 1700  
an Chen

**Examiner:** Kin Chan Chen

**CERTIFICATE OF MAILING**  
**37 CFR 1.8**

I hereby certify that this correspondence is being deposited on 5/21, 2003 with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450.

5/21/03 Kristen R. [Signature]  
Date Signature

**RESPONSE TO RESTRICTION REQUIREMENT DATED APRIL 24, 2003**

In response to the Restriction Requirement dated April 24, 2003, having a shortened statutory period for response set to expire on May 24, 2003, please enter this response and reconsider the claims pending in the application for reasons discussed below. Although Applicants believe that no fee is due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/AMAT/6060/KMT, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

1. A method of planarizing a metal conductive layer on a top surface of a substrate, comprising:

- Page 1